MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

Meets or Exceeds the Requirements of D, N, OR NS PACKAGE (TOP VIEW) ANSI Standards EIA/TIA-422-B and **EIA/TIA-423-B and ITU Recommendations** 1B 16 VCC V.10 and V.11 1A [15 AB 3-State, TTL-Compatible Outputs 14 🛮 4A 1Y **∏** 3 **Fast Transition Times** 1.2EN **∏** 4 13 T 4Y **Operates From Single 5-V Supply** 12 3,4EN 2Y 🛮 2A 11 3Y Designed to Be Interchangeable With 2B **∏** 7 10 3A Motorola™ MC3486 9 1 3B GND

description

The MC3486 is a monolithic quadruple differential line receiver designed to meet the specifications of ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B and ITU Recommendations V.10 and V.11. The MC3486 offers four independent differential-input line receivers that have TTL-compatible outputs. The outputs utilize 3-state circuitry to provide a high-impedance state at any output when the appropriate output enable is at a low logic level.

The MC3486 is designed for optimum performance when used with the MC3487 quadruple differential line driver. It is supplied in a 16-pin package and operates from a single 5-V supply.

The MC3486 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

	PACKAGED DEVICES					
TA	PLASTIC SMALL OUTLINE (D, NS)	PLASTIC DIP (N)				
0°C to 70°C	MC3486D MC3486NS	MC3486N				

The D package is available taped and reeled. Add the suffix R to the device type (e.g., MC3486DR). The NS package is only available taped and reeled.



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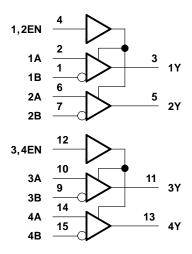


FUNCTION TABLE (each receiver)

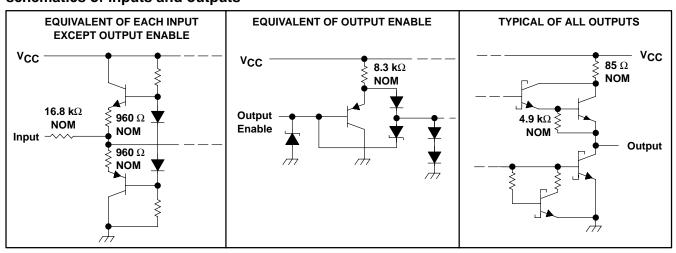
DIFFERENTIAL INPUTS A-B	ENABLE	OUTPUT Y
V _{ID} ≤ 0.2 V	Н	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	Н	?
$V_{ID} \le -0.2 V$	Н	L
Irrelevant	L	Z
Open	Н	?

H = high level, L = low level, Z = high impedance (off), ? = indeterminate

logic diagram (positive logic)



schematics of inputs and outputs





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	8 V
Input voltage, V _I (A or B inputs)	
Differential input voltage, V _{ID} (see Note 2)	
Enable input voltage	
Low-level output current, IOL	50 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	
N package	67°C/W
NS package	67°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential-input voltage, are with respect to network ground terminal.
 - 2. Differential-input voltage is measured at the noninverting input with respect to the corresponding inverting input.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIC	Common-mode input voltage			±7	V
VID	Differential input voltage			±6	V
VIH	High-level enable input voltage	2			V
VIL	Low-level enable input voltage			0.8	V
TA	Operating free-air temperature	0		70	°C

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electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT		
VIT+	Differential input high-threshold voltage	$V_O = 2.7 \text{ V}, \qquad I_O = -0.4 \text{ mA}$			0.2	V	
V_{IT-}	Differential input low-threshold voltage	$V_{O} = 0.5 \text{ V}, \qquad I_{O} = -8 \text{ mA}$		-0.2†		V	
٧ _{IK}	Enable-input clamp voltage	$I_I = -10 \text{ mA}$			-1.5	٧	
VOH	High-level output voltage	$V_{\text{ID}} = 0.4 \text{ V},$ $I_{\text{O}} = -0.4 \text{ mA},$ See Note 4 and Figure 1		2.7		٧	
VOL	Low-level output voltage	$V_{\mbox{\scriptsize ID}} = -0.4 \mbox{ V}, \qquad \mbox{\scriptsize I}_{\mbox{\scriptsize O}} = 8 \mbox{\scriptsize mA},$ See Note 4 and Figure 1			0.5	٧	
	Lligh impodence state systems surrent	$V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = -3 \text{ V}, \qquad V_{C}$	o = 2.7 V		40		
loz	High-impedance-state output current	$V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = 3 \text{ V}, \qquad V_{C}$	o = 0.5 V		-40	μΑ	
		V _I	=-10 V		-3.25		
	Differential-input bias current	V _{CC} = 0 V or 5.25 V,	=-3 V		-1.5	mA	
IВ	Differential-input bias current	Other inputs at 0 V	= 3 V		1.5	mA	
		VI	= 10 V		3.25		
1	High-level enable input current	V _I = 5.25 V			100		
lιΗ	nigir-level eriable input current	V _I = 2.7 V			20	μΑ	
IIL	Low-level enable input current	V _I = -0.5 V			-100	μΑ	
los	Short-circuit output current	$V_{ID} = 3 V$, $V_O = 0$, See	ee Note 5	-15	-100	mA	
ICC	Supply current	V _{IL} = 0			85	mA	

[†] The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet for threshold voltages only.

NOTES: 4. Refer to ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

5. Only one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPHL	Propagation delay time, high- to low-level output	See Figure 2		28	35	ns
tPLH	Propagation delay time, low- to high-level output	See Figure 2		27	30	ns
^t PZH	Output enable time to high level			13	30	ns
tPZL	Output enable time to low level	See Figure 3		20	30	ns
tPHZ	Output disable time from high level	See Figure 3		26	35	ns
^t PLZ	Output disable time from low level			27	35	ns



PARAMETER MEASUREMENT INFORMATION

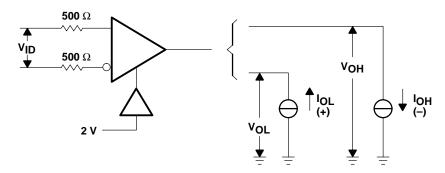
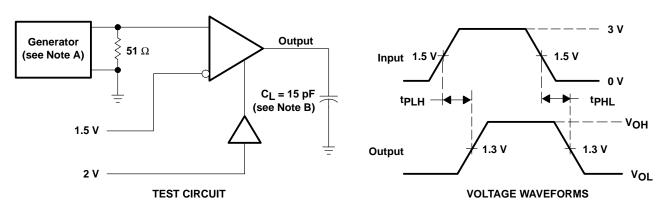


Figure 1. V_{OH}, V_{OL}

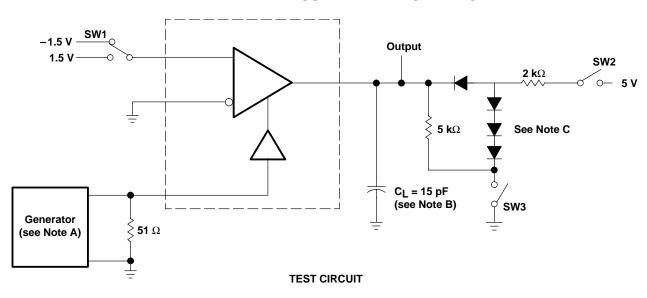


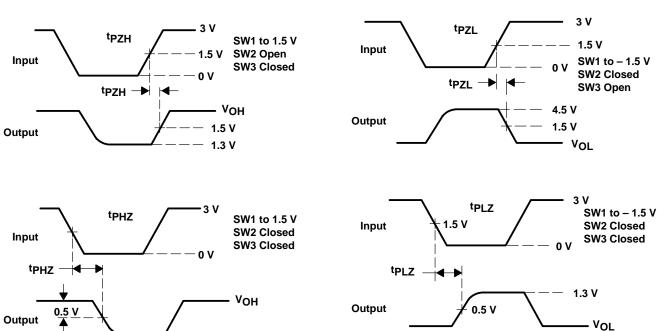
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_{f} \leq$ 6 ns, $t_{f} \leq$ 6 ns.

B. C_L includes probe and stray capacitance.

Figure 2. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION





NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns.

B. CL includes probe and stray capacitance.

1.3 V

C. All diodes are 1N916 or equivalent.

Figure 3. Test Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
MC3486D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
MC3486N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MC3486NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MC3486NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

4-Jun-2007

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

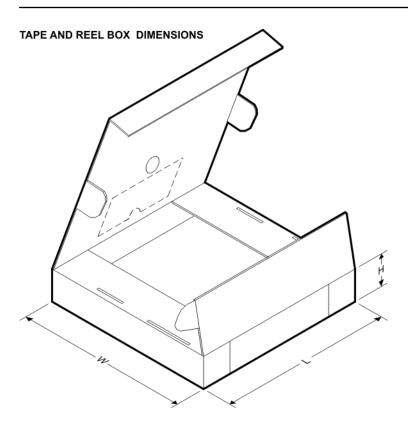
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MC3486DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
MC3486NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC3486DR	SOIC	D	16	2500	333.2	345.9	28.6
MC3486NSR	SO	NS	16	2000	346.0	346.0	33.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDS0-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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